

| External_Type  | Material_Group  | Substances                                             | CAS_Number | Mass  | Mass_Percentage_in_Leaf | Massmg  |
|----------------|-----------------|--------------------------------------------------------|------------|-------|-------------------------|---------|
| Die            | Doped silicon   | Silicon (Si)                                           | 7440-21-3  | 0.08  | 100.0                   | 1.6     |
| Subtotal       |                 |                                                        |            | 0.08  | 100                     | 1.6     |
| Solder Wire    | Lead alloy      | Tin (Sn)                                               | 7440-31-5  | 0     | 2.0                     | 0.03    |
|                | Lead alloy      | Silver (Ag)                                            | 7440-22-4  | 0     | 2.5                     | 0.04    |
|                | Lead alloy      | Lead (Pb)                                              | 7439-92-1  | 0.07  | 95.5                    | 1.42    |
| Subtotal       |                 |                                                        |            | 0.07  | 100                     | 1.49    |
| Wire           | Pure metal      | Aluminium (Al)                                         | 7429-90-5  | 0.01  | 100.0                   | 0.26    |
|                | Pure metal      | Aluminium (Al)                                         | 7429-90-5  | 0.05  | 100.0                   | 1.02    |
| Subtotal       |                 |                                                        |            | 0.06  | 200                     | 1.28    |
| Lead Frame     | Copper alloy    | Phosphorous (P)                                        | 7723-14-0  | 0.02  | 0.03                    | 0.4     |
|                | Copper alloy    | Iron (Fe)                                              | 7439-89-6  | 0.04  | 0.06                    | 0.8     |
|                | Copper alloy    | Copper (Cu)                                            | 7440-50-8  | 67.41 | 99.91                   | 1338.79 |
| Subtotal       |                 |                                                        |            | 67.47 | 100                     | 1339.99 |
| Post-plating   | Pure metal      | Tin (Sn)                                               | 7440-31-5  | 1.04  | 100.0                   | 20.68   |
| Subtotal       |                 |                                                        |            | 1.04  | 100                     | 20.68   |
| Mould Compound |                 | Tetrabromobisphenol A/Epichlorohydrin polymer          | 40039-93-8 | 0.22  | 0.7                     | 4.35    |
|                | Polymer         | Phenol Formaldehyde resin (generic)                    | 9003-35-4  | 1.88  | 6.0                     | 37.26   |
|                | Polymer         | Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) | 25928-94-3 | 3.75  | 12.0                    | 74.52   |
|                | Filler          | Silica fused                                           | 60676-86-0 | 21.89 | 70.0                    | 434.7   |
|                | Carbon Black    | Carbon black                                           | 1333-86-4  | 0.09  | 0.3                     | 1.86    |
|                | Filler          | Misc. Silica compounds (generic)                       | 14808-60-7 | 3.13  | 10.0                    | 62.1    |
|                | Flame retardant | Antimony Trioxide (Sb2O3) - cas no. 1309-64-4          | 1309-64-4  | 0.31  | 1.0                     | 6.21    |
| Subtotal       |                 |                                                        |            | 31.27 | 100                     | 621     |
| Total          |                 |                                                        |            | 99.99 | 100                     | 1986.04 |

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